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Assistant Commissioner for Patents  
Washington, D.C. 20231

PATENT  
Attorney Docket No.: A4142/T40300

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FEB 03 2003

TOWNSEND and TOWNSEND and CREW LLP

By: *[Signature]*

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

HARI PONNEKANTI et al.

Application No.: 09/502,126

Filed: February 10, 2000

For: A PROCESS AND AN  
INTEGRATED TOOL FOR LOW  
K DIELECTRIC DEPOSITION  
INCLUDING A PECVD  
CAPPING MODULE

Examiner: Karla A. Moore

Art Unit: 1763

AMENDMENT

#170  
2/8/03  
MW

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BOX FEE AMENDMENT

Assistant Commissioner for Patents  
Washington, D.C. 20231

Sir:

In response to the Office Action mailed August 27, 2002, for which a two month extension of time from November 27, 2002 to January 27, 2003 is enclosed, please amend the above-identified application as follows:

IN THE SPECIFICATION:

Paragraph beginning at line 10 of page 4 has been amended as follows:

Figure 1 illustrates a vacuum cluster tool 10 having multiple single substrate processing chambers 12 mounted on a centralized vacuum chamber, called a transfer chamber 18, for transferring substrates from a substrate cassette located in one or more loadlock chambers 20, to one or more process chambers 12. This particular tool is shown to accommodate up to four (4) single substrate processing chambers 12 positioned radially about the transfer chamber. A cluster tool similar to that shown in Figure 1 is available from Applied Materials, Inc. of Santa Clara, California. The transfer of the substrates between the process chambers 12 is typically managed by a substrate handling module 16 located in a central transfer chamber 12. After the substrates are processed, they are moved back through the loadlock chamber 20 and into substrate cassettes where the substrates can be moved to the next system for additional

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